

*Application Note*

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MPC8xx Using BDM and  
JTAG

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As the technical complexity of microprocessors has increased, so too has the need for adequate resources to enable efficient debugging and system testing. This application note explains the functional and configurational differences between background debug mode (BDM) and the IEEE 1149.1 test access port (TAP) of the MPC8xx device family. An overview of each of the test mechanisms is followed by the basic operation and system interfaces.

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## 1.1 References

Users should familiarize themselves with the MPC860 PowerQUICC™ Family User Manual (MPC860UM/D) and the Programming Environments Manual for 32-Bit Implementations of the PowerPC™ Architecture, (MPEFPC32B/AD) .

These manuals can be downloaded from the MPC860 web-page:

Click on the link below to go to the Freescale Semiconductor Products Sector homepage:

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The IEEE 1149.1 JTAG specification is also recommended reading for those unfamiliar with JTAG.

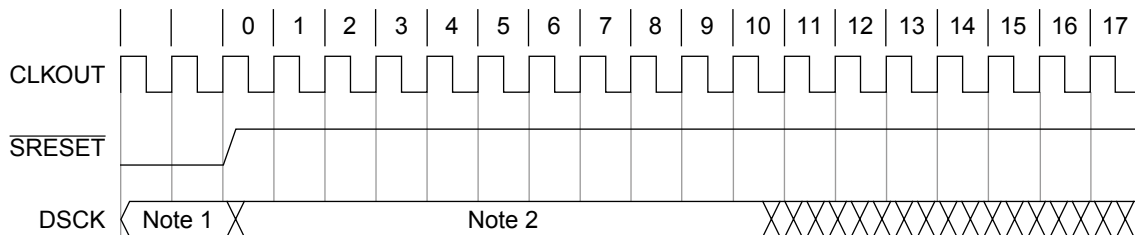
## 1.2 Overview of BDM

Before the introduction of BDM, the options available to users for debugging were limited to either ROM monitors or in-circuit emulators (ICE). The former typically entails debugging code that has been downloaded to RAM, requiring the same memory space as if burned into ROM. To communicate with the external debugger, the ROM monitor also requires an interface that may be internal to the device, which can degrade device performance, or an external interface, which increases board size. The other alternative, the ICE, allows greater flexibility in the control of the processor including real-time tracing, programming model access and hardware breakpoints, without using processor resources. However, since it requires the bond-out of additional signals, along with external memory and specialized cables, it is considered an expensive outlay for development.

BDM is implemented on the MPC8xx to overcome the limitations of the ROM monitor and without the expense of ICE. This is achieved via some of the development support functions on the device, which will be explained later in the document. A full-duplex serial interface, allows communications between the development port support logic and the development tool. This allows program flow tracking, along with internal watchpoint and breakpoint generation. More importantly, single step debugging allows memory and registers to be examined at any point.

## 1.3 Operation of BDM

The development port can operate in two modes, either trap enable mode or debug mode. When in trap enable mode the development port receives a 10 bit transmission from the development tool. These transmissions are used to control the on-chip breakpoint functions and the debug port commands. In debug mode all (32-bit) instructions are fetched from the development port and are fed into the processor to be executed, with load/store accesses performed on the real system memory. Debug mode operation is enabled at reset by the assertion of DSCK at least three clocks before the negation of  $\overline{\text{SRESET}}$ , as shown in Figure 1-1. If DSCK is then asserted past the  $\overline{\text{SRESET}}$  negation, the processor takes a breakpoint exception and goes directly into debug mode instead of fetching the reset vector. This allows the user to debug a ROM-less system. If debug mode is not required directly after reset then DSCK must be negated no later than seven clock cycles after the negation of  $\overline{\text{SRESET}}$ .



Notes:

1. DSCK asserts high while  $\overline{\text{SRESET}}$  asserted to enable debug mode operation.
2. DSCK asserts high after  $\overline{\text{SRESET}}$  negation to enter debug mode immediately (without fetching reset vector).

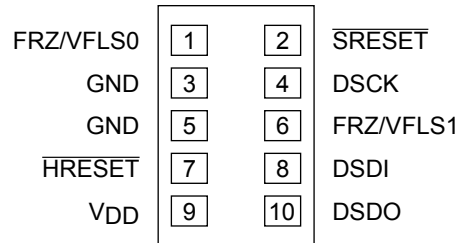
Figure 1-1. Debug mode entry

The Debug Enable Register (DER) allows the user to selectively enable events that cause the processor to enter debug mode. Interrupt events are reported in the Interrupt Cause Register (ICR). This results in entry

into debug mode only if the corresponding bit in the DER is set and debug mode is enabled. After debug mode entry, program execution will continue from the point at which debug mode was entered. To exit from debug mode use the **rfi** instruction. This returns the processor to normal operation and negates the FRZ/FLS pins.

## 1.4 System Interface

The BDM signals communicate with the development tool through the development port interface. This consists of several pins on the device that are routed to a 10-pin dual-row header on the user's board, as shown in Figure 1-2.



**Figure 1-2. BDM connector Pinout**

The Development Serial Clock (DSCK) is used at reset to enable debug mode. This can be entered either immediately following reset or on the occurrence of an event reported in the ICR. DSCK is an input to the development port and must be driven either high or low at all times. It must not be allowed to float. It is therefore recommended to connect this pin to a pull-down resistor to prevent accidental entry to debug mode. The DSCK is also used to clock the data in and out of the development port shift register, when in asynchronous clocked mode, so called because DSCK is asynchronous with CLKOUT. Another clock mode available, called synchronous self-clocked, does not require the input clock. Instead, the port is clocked via the system clock. The selection between these two clock modes occurs at reset. The DSDI input is latched eight clocks after the negation of  $\overline{\text{SRESET}}$ . If the input is low, then asynchronous clocked mode is enabled, otherwise synchronous self-clocked mode is enabled.

The Development Serial Data In (DSDI) pin receives data from the development tool, which is shifted serially into the development port shift register.

The Development Serial Data Out (DSDO) pin transmits data out of the development port shift register back to the development tool.

The Freeze (FRZ) pin indicates that the processor is in debug mode, which can be used to halt any off-chip device and allows a handshake between the development port and tool. When the FRZ signal is asserted, the clocks to the software watchdog, PIT, real-time clock, timebase counter, and decremter can be disabled. This is controlled by the associated bits in the control register of each timer. If they are programmed to stop counting when FRZ is asserted, the counters maintain their values until FRZ is negated. However, the bus monitor, will be enabled regardless of the state of this signal.

To allow the development tool to reset the processor, both  $\overline{\text{HRESET}}$  and  $\overline{\text{SRESET}}$  must be included on the BDM header. The VDD pin is also required and provides a power sense to the development tool.

## 1.5 Pin muxing

The development port pins are multiplexed with other pins on the device, as shown in Figure 1-3, and are available in two locations. This allows the user greater flexibility when designing a system, in case of any conflict with the shared function.

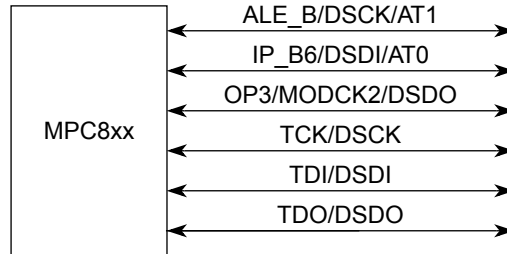


Figure 1-3. Development Port pin-muxing

The location of these pins is determined during  $\overline{\text{HRESET}}$  by configuring the [DBPC] bits in the Hard Reset Configuration Word. After reset the configuration set-up is loaded into the corresponding bits of the SIU Module Configuration Register (SIUMCR). Any subsequent  $\overline{\text{SRESET}}$  will load the pin as per the configuration set-up in the SIUMCR.

The FRZ pin is multiplexed with  $\overline{\text{IRQ6}}$  and is selected by clearing SIUMCR[FRC], although the reset value defaults to FRZ. Optionally, the VFLS0/VFLS1 pins can replace the FRZ pin and the value of 0b11 on these pins also indicates debug mode. However, since these pins also share pin muxing, to be selected requires [DBGC] = 0b11 in the Hard Reset Configuration Word.

The Hard Reset Configuration Word is used during a  $\overline{\text{PORESET}}/\overline{\text{HRESET}}$  to determine the initial mode of operation. This is achieved by asserting the  $\overline{\text{RSTCONF}}$  signal, which instructs the MPC8xx to sample the values present on the data-bus, otherwise the internal default value (0x00) is selected. When the  $\overline{\text{PORESET}}$  is negated, the data-bus is sampled every nine clock cycles, on the rising edge of CLKOUT. The set-up time required for the data bus is 15 cycles, while the maximum rise time of  $\overline{\text{HRESET}}$  should be less than six clock cycles, as shown in Figure 1-4.

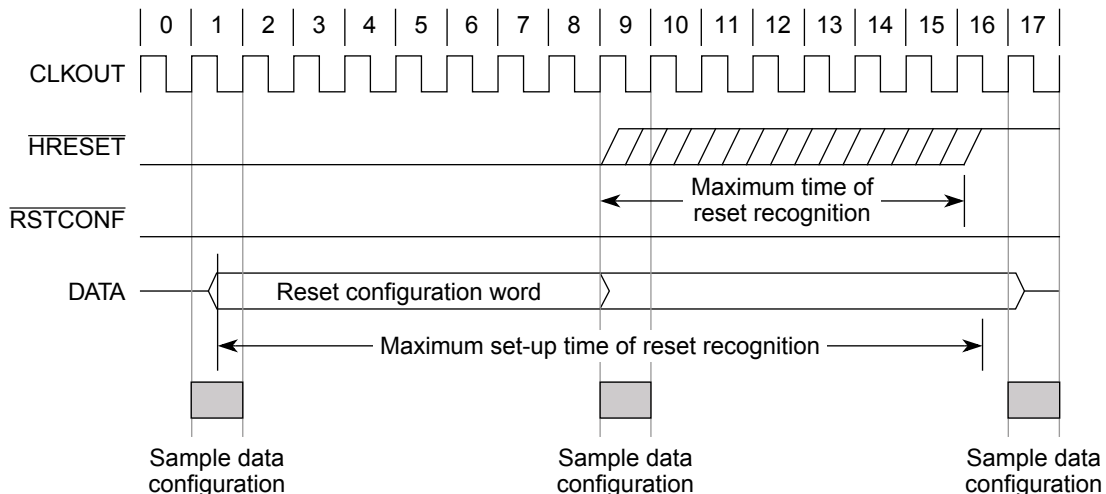


Figure 1-4. Hard Reset Configuration Word Sampling Timing

## 1.6 Overview of JTAG

The conventional methods used to test printed circuit boards (PCBs) involved methods such as the Edge Connector Test and the “Bed of Nails” Test. However, with introduction of high pin-count devices with fine pitch, along with multi-layer PCBs, these methods are no longer adequate or cost-effective in testing.

During the 1980’s the Joint Test Action Group (JTAG) was formed from over 200 companies to address these issues. They subsequently developed a standard for integrating hardware into standard devices, that could be controlled by software. This was termed Boundary Scan Testing (BST). This was later adopted by the IEEE and defined as the *IEEE 1149.1 Standard Test Access Port and Boundary Scan Architecture*. The MPC8xx family provides a test access port (TAP) that is compatible with this standard.

## 1.7 TAP interface

The *test logic* consists of a 4-bit instruction register and two data registers (a 1-bit bypass register and a 475 bit boundary scan register). Manipulation of these registers is controlled using the TAP controller state machine, whose sequence is controlled using the Test mode select (TMS) input. The registers are modified by data from the serial test data input pin (TDI), with output results visible on the serial test data out pin (TDO). The TDO pin is tri-stated when data is not being driven out the device. An active low asynchronous reset (with an internal pull-up resistor) is used to initialize the TAP controller.

The Boundary Scan Register is a 475-bit serial shift register that contains bits for all signals, with the exception of XTAL, EXTAL and XFC pins, which are analog signals. When the device is functioning normally the boundary scan circuitry is inactive. However when the test mode is entered the boundary scan cells that are contained in each pin are connected together to form a scan chain between TDI and TDO, as shown in Figure 1-5. This allows electrical testing of devices such as connectivity tests, ensuring there are no opens or shorts on the board.

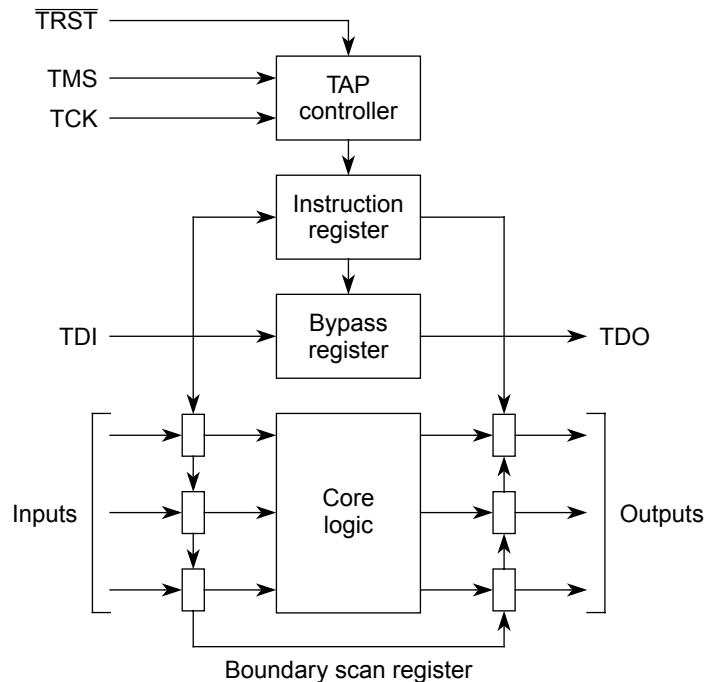


Figure 1-5. Boundary Scan Test Logic

## TAP interface

The TAP implements an instruction register, as required by the IEEE 1149.1 standard, which is 4-bits wide, with no parity. The four instruction bits select the three required and two optional instructions as shown in Table 1-1.

**Table 1-1. Instruction Register Decoding**

Code				Instruction
B3	B2	B1	B0	
0	0	0	0	EXTEST
0	0	0	1	SAMPLE/PRELOAD
0	X	1	X	BYPASS
0	1	0	0	HI-Z
0	1	0	1	CLAMP & BYPASS

The instruction register selects the BYPASS instruction by default, during the test-logic-reset state.

The external test (EXTEST) instruction places the device into external boundary test mode and connects the 475-bit boundary scan register between TDI and TDO. EXTEST also asserts an internal soft reset for the MPC8xx system logic to force to a known beginning internal state while performing external boundary scan operations.

The BYPASS instruction allows data to pass through the device during normal operation by placing the 1-bit bypass register between the TDI and TDO pins. The data does not enter the boundary scan chain and is therefore used to enhance test efficiency when another device, other than the MPC8xx is being tested.

The SAMPLE/PRELOAD instruction connects the boundary scan register between TDI and TDO, while allowing the device to remain in its normal mode of operation. This enables the boundary scan register to take a sample of the data entering and leaving the device.

The TCK, TDI and TDO pins are multiplexed with the development port pins. They are configured in the DBPC bits of the Hard Reset Configuration Word, which is loaded from the data bus, during the assertion of HRESET and RSTCONF. If RSTCONF is not asserted during this time the default value of 0x0 will be selected. To ensure the TAP interface functions correctly it is necessary to configure the DBPC bits [D11/D12] as shown in Table 1-2

**Table 1-2. Debug Port Configuration**

DBPC=00	DBPC=01	DBPC=10	DPBC=11
Defined by DBGCC. <b>Note:</b> If DPBC = 11, DPBC overrides DBGCC.		Reserved	DSCK
			DSDI
			DSDO
			PTR*
DSCK	TCK		TCK
DSDI	TDI		TDI
DSDO	TDO	TDO	

If both the BDM and TAP ports are required then DPBC must be set to 0x11, as shown in the last column of Table 1-2.

The TAP controller remains in the test-logic-reset state after power-on and is disabled to allow the device to function normally. To enter JTAG mode set TMS=0. The default on entering JTAG mode is for the core to come up in a state equivalent to BYPASS mode. In this mode a 1bit shift register path is created between TDI, through the bypass register to TDO.

A simple way to indicate that the MPC8xx is in JTAG mode is to enter the default BYPASS mode, clock a bit stream into TDI and monitor the bit stream coming back out on TDO 1 cycle later. Assertion of FRZ signal indicates that the core is in debug mode and therefore the entry conditions for JTAG have not been met.

## 1.8 TAP Configuration

The TAP signals must be configured as follows to reset the scan chain logic:

- If both the TAP and low power mode are never used, connect  $\overline{\text{TRST}}$  to ground.
- If the TAP or low power mode is used, connect  $\overline{\text{TRST}}$  to  $\overline{\text{PORESET}}$ .
- If power down mode (the lowest power mode, where VDDH is disabled) is used, connect  $\overline{\text{TRST}}$  to  $\overline{\text{PORESET}}$  through a diode (anode to  $\overline{\text{TRST}}$ , cathode to  $\overline{\text{PORESET}}$ ).

The TMS, TDI, and  $\overline{\text{TRST}}$  signals include on-chip pull-up resistors. However, TCK does not have an on-chip pull-up or pull-down resistor; it should be pulled down through a (10k) resistor. TCK should not be greater than 10MHz since this is the maximum frequency allowed.

## 1.9 Boundary Scan Descriptor Language

The Boundary Scan Descriptor Language (BSDL), which is a subset of VHDL, was devised to standardize the method of describing the boundary-scan architectures detailed in the IEEE 1149.1 specification. This allows designers and test software developers to generate test patterns and perform in-circuit programming. The BSDL file for the MPC860 can be found on the web, as described in Section 1.1, “References”.

## 1.10 Conclusion

The challenges of the debugging and testing of high pin count microprocessors on densely populated circuit boards have been overcome on the MPC8xx devices. This has been achieved by integrating BDM and JTAG support functions on silicon with access via a simple interface for each. These features are easily implemented without taking up valuable board space, resulting in increased efficiency in the user's system development, while simultaneously reducing cost.

# Appendix A

## Typical Set-up Questions and Answers

The following questions are frequently asked during the set-up phase.

*When the 8xx is in BDM, if the cache is enabled, will the cache respond to accesses to external memory? That is, if you try to read/write memory from the core when in BDM, will caches intervene and respond?*

When you are in BDM, caches are frozen. You can read/write the registers of the cache, and thereby look into it, but the cache will not try to operate in its normal fashion. This is true regardless of the mode that the cache was in before entry into BDM.

*Can the FRZ signal pin be substituted in place of VFLS(0:1) on MPC8xx BDM interface without affecting debug mode functionality?*

If you don't plan on using the trace function, then you don't need the VFLS pins. FRZ is not a substitute for VFLS, their function (as described in the Development Support section of the User Manual) is completely different.

*In BDM, while accessing memory, is the device's operation is stopped?*

In BDM the MPC8xx core is held in a frozen state and will only accept instructions from the BDM port. If no instructions are issued the core remains frozen i.e. its operation is stopped until the next instruction appears on the BDM port. The MPC8xx should not fall over in the middle of a memory access. If the cycle completes for example writing to internal memory and there is no more instructions to process the processor will stop.

*Do the instructions that come from the development port use physical addresses instead of logical addresses. The user manual indicates that instructions from development port perform accesses on the real system memory. Does it mean physical memory?*

Physical addressed memory is referred to as real addresses in the architecture specification.

*What happens after a Soft reset ( $\overline{SRESET}$ )?*

When a soft reset event occurs the MPC8xx will reconfigure the development port, depending on the user's settings.. The user should ensure there are no spurious writes to the SIUMCR that could corrupt the debug port / pin configurations.

*How should the TAP be configured to prevent accidental entry to JTAG?*

To ensure that the scan chain test logic is kept transparent to the system logic during normal operation, the TAP should be forced into the test-logic-reset controller state by keeping  $\overline{TRST}$  or TMS continuously asserted.

*If the MPC8xx starts executing from FLASH after power-up and enters JTAG mode, will it continue to execute the code from FLASH?*

This depends on which state the JTAG port is configured in coming out of reset. When the BYPASS mode of operation is selected, all of the test registers in the MPC8xx perform their normal system function.

*What will the core of the MPC8xx do when it is in JTAG mode?*

The default on entering JTAG mode is for the core to come up in a state equivalent to BYPASS mode. In this mode a 1bit shift register path is created between TDI, through the bypass register to TDO. A simple way to indicate that the MPC8xx is in JTAG mode is to enter the default BYPASS mode, clock a bit stream into TDI and monitor the bit stream coming back out on TDO 1 cycle later.

*Is assertion of FRZ expected in JTAG mode?*

Assertion of FRZ signal indicates that the core is in debug mode and therefore the entry conditions for JTAG have not been met.

*If SIUMCR [DBGC and DBPC] are latched during the PORESET can they be modified afterwards by software?*

The user can write to these fields at any time as long as SIUMCR[DLK] is not asserted.

*TRST must be asserted at least initially to set up JTAG. If  $\overline{TRST}$  remains low, can JTAG still be used by pulling TMS to 0 and clocking TCK?*

$\overline{TRST}$  cannot remain low, but must be pulled low initially.

*Will JTAG work if the clock input to the processor is held inactive? Will the PLL never lock?*

Boundary scan testing should still be possible with the clock input to the processor held inactive - its operation decouples the processor system clock prior to testing. However, any non-scan testing the user plans to do such as checking registers, will require some form of clock functionality. If the PLL experiences a loss of lock (PLPRCR[LOLRE]=1) an internal hard reset will occur. If the user attempts to start the processor clock from this inactive state, they should not expect the PLL to function correctly. It requires stable input clocks to operate.

*Is the software watchdog disabled in BDM and JTAG mode?*

The software watchdog configuration will be the same as was set up in the system protection control register SYPCR[SWE], when JTAG is enabled. The user will need to take into account any resets to the MPC8xx as JTAG is entered. The watchdog timer has to be disabled manually. The same applies to BDM. Out of reset, if JTAG is enabled and is being used for board testing, i.e. continuity testing, and not to monitor the chip internals, then the fact that the Watchdog times out and  $\overline{HRESET}$  is asserted should not matter.





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